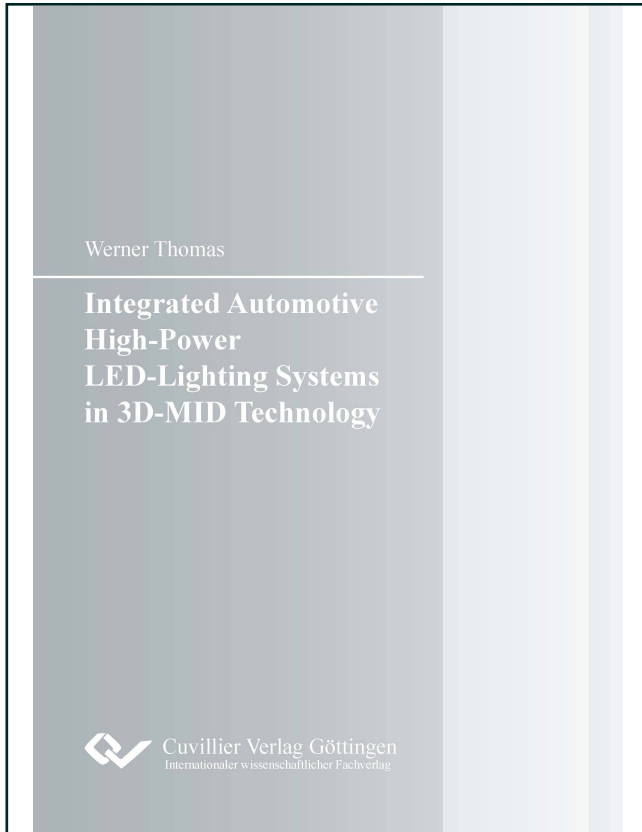




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Integrated Automotive High-Power LED-Lighting Systems in 3D-MID Technology



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